

PRINTING STENCILS FOR ELECTRONIC SUBSTRATES

ABSTRACT

Stencils are provided for more precisely aligning stencil orifices with terminals or "targets" on a substrate. One such stencil is adapted for registration with an electronic substrate, such as a PCB, about a locus. The stencil includes a stencil body and an array of printing orifices passing through the stencil body. The printing orifices may have varying sizes, with the size of each printing orifice being a function of a distance of the printing orifice from the locus. Various methods are also provided, including methods for applying solder on electronic substrates using stencils and methods and systems for designing such stencils.